



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250516004.1
Qualify MLA as an additional Assembly site for select devices
Change Notification / Sample Request

Date: May 20, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services




20250516004.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
PCM1796DBR	PCM1796DBR
DSD1793DB	NULL
PCM2903CDBR	PCM2903CDBR
PCM2906CDB	NULL
PCM2900CDBR	NULL
PCM2704DB	NULL
PCM2900CDB	NULL
PCM2906BDB	NULL
PCM2704CDB	NULL
PCM2902CDB	NULL
PCM1791ADB	NULL
PCM1804DBR	PCM1804DBR
PCM2902CDBR	NULL
PCM2906CDBR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250516004.1		PCN Date:	May 20, 2025												
Title:	Qualify MLA as an additional Assembly site for select devices															
Customer Contact:	Change Management team		Dept:	Quality Services												
Proposed 1st Ship Date:	August 18, 2025		Sample requests accepted until:	July 19, 2025*												
*Sample requests received after July 19, 2025 will not be supported.																
Change Type:																
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material														
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process														
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site														
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material														
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process														
PCN Details																
Description of Change:																
Texas Instruments is pleased to announce the qualification of TI Malaysia (MLA) as an additional Assembly site for the list of devices shown below. Material differences between sites are as follows.																
<table border="1"> <thead> <tr> <th></th> <th>NST</th> <th>MLA</th> </tr> </thead> <tbody> <tr> <td>Wire type/diam</td> <td>1.0mil Au</td> <td>1.0mil Cu</td> </tr> <tr> <td>Mount compound</td> <td>P194</td> <td>4147858</td> </tr> <tr> <td>Mold compound</td> <td>R0192</td> <td>4211880</td> </tr> </tbody> </table>						NST	MLA	Wire type/diam	1.0mil Au	1.0mil Cu	Mount compound	P194	4147858	Mold compound	R0192	4211880
	NST	MLA														
Wire type/diam	1.0mil Au	1.0mil Cu														
Mount compound	P194	4147858														
Mold compound	R0192	4211880														
Reason for Change:																
Continuity of supply.																
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																
None.																
Impact on Environmental Ratings																
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																
RoHS	REACH	Green Status	IEC 62474													
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change													
Changes to product identification resulting from this PCN:																
Assembly Site																
NST	Assembly Site Origin (22L)	ASO: HHS														
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA														
Sample product shipping label (not actual product label)																
<div style="display: flex; justify-content: space-between;"> <div>  <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL 2 / 260C/1 YEAR MSL 1 / 235C/UNLIM OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div>  </div> <div>  </div> <div> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>																

Product Affected:

DSD1793DB	PCM1802DBR	PCM2900BDBR	PCM2903CDB
DSD1793DBR	PCM1804DB	PCM2900CDB	PCM2903CDBR
DSD1796DB	PCM1804DBG4	PCM2900CDBR	PCM2906BDB
DSD1796DBR	PCM1804DBR	PCM2900E	PCM2906BDBR
PCM1791ADB	PCM1804DBRG4	PCM2900E/2K	PCM2906BS1DB
PCM1791ADBR	PCM1804S1DBR	PCM2902BDB	PCM2906BS1DBR
PCM1796DB	PCM2704CDB	PCM2902CDB	PCM2906CDB
PCM1796DBR	PCM2704CDBR	PCM2902CDBR	PCM2906CDBR
PCM1802DB	PCM2704DB	PCM2903BDB	SN001796DBR
PCM1802DBG4	PCM2704DBR	PCM2903BDBR	

Qualification Report

Approve Date 12-August-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: PCM1802DB	Qual Device: PCM1804DB	QBS Reference: TPD3S714QDBQRQ1	QBS Reference: PTRSF3243EIDBR
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	1/76/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	1/76/0
SD	C3	PB Solderability	Post 8hr steam	-	-	-	3/45/0	-
SD	C3	PB-Free Solderability	Post 8hr steam	-	-	-	3/45/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	3/9/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	4000 Volts	-	-	3/9/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	3/18/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	-

QBS: Qual By Similarity

Qual Device PCM1802DB is qualified at MSL1 260C

Qual Device PCM1804DB is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2210-098

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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